



Click [here](#) for the 3D model.

### Dimensions

|           |                  |
|-----------|------------------|
| Chip Size | 0805             |
| L         | 2mm +/-0.2mm     |
| W         | 1.25mm +/-0.2mm  |
| T         | 0.78mm +/-0.10mm |
| S         | 0.75mm MIN       |
| B         | 0.5mm +/-0.25mm  |

### Packaging Specifications

|                    |                        |
|--------------------|------------------------|
| Packaging          | T&R, 180mm, Paper Tape |
| Packaging Quantity | 4000                   |

### General Information

|                  |  |
|------------------|--|
| Series           | SMD Comm COG                               |
| Style            | SMD Chip                                   |
| Description      | SMD, MLCC, Ultra-Stable, Low Loss, Class I |
| Features         | Ultra-Stable, Low Loss, Class I            |
| RoHS             | Yes  |
| Termination      | Tin  |
| Marking          | No   |
| AEC-Q200         | No   |
| Component Weight | 11 mg                                      |
| Shelf Life       | 78 Weeks                                   |
| MSL              | 1  |

### Specifications

|  |                        |
|--|------------------------|
| Capacitance  | 30 pF                  |
| Measurement Condition  | 1MHz 1.0Vrms           |
| Capacitance Tolerance  | 5%                     |
| Voltage DC   | 25 VDC                 |
| Dielectric Withstanding Voltage                                    | 62.5 VDC               |
| Temperature Range  | -55/+125°C             |
| Temperature Coefficient  | COG                    |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MHz 1.0Vrms |
| Dissipation Factor   | 0.1% 1 MHz 1.0Vrms     |
| Aging Rate   | 0% Loss/Decade Hour    |
| Insulation Resistance  | 100 GOhms              |